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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Itsuo WATANABE et al.) Atty. Docket: TM&K0013
Serial No. 09/402,274) Group Art Unit: 1775
Filed: December 16, 1999) Examiner: M. E. LAVILLA
For: CIRCUIT-CONNECTING MATERIAL)
AND CIRCUIT TERMINAL CON-)
NECTED STRUCTURE etc.) Date: December 18, 2002

AMENDMENT (B)

BOX: NO FEE RESPONSE
Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

In response to the official Office Action dated June 18, 2002, please amend the above-captioned application as follows.

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more; and
- (3) a radical-polymerizable substance.

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01 FC:1201 84.00 CH
02 FC:1202 18.00 CH